

■ RECOMMENDED DC OPERATING CONDITIONS ($T_a = 0$ to $+70^\circ\text{C}$)

Item	Symbol	min	typ	max	Unit
Supply Voltage	V_{CC}	4.5	5.0	5.5	V
	GND	0	0	0	V
Input Voltage	V_{IH}	2.2	–	6.0	V
	V_{IL}	-0.3*	–	0.8	V

* Pulse Width 50ns: -3.0V

■ DC AND OPERATING CHARACTERISTICS ($V_{CC} = 5V \pm 10\%$, GND = 0V, $T_a = 0$ to $+70^\circ\text{C}$)

Item	Symbol	Test Condition	min	typ*	max	Unit
Input Leakage Current	I_{LI}	$V_{in} = \text{GND to } V_{CC}$	–	–	2	μA
Output Leakage Current	I_{LO}	$\overline{\text{CS}}1 = V_{IH}$ or $\text{CS}2 = V_{IL}$ or $\overline{\text{OE}} = V_{IH}$ or $\overline{\text{WE}} = V_{IL}$, $V_{I/O} = \text{GND to } V_{CC}$	–	–	2	μA
Operating Power Supply Current	I_{CC}	$\overline{\text{CS}}1 = V_{IL}$, $\text{CS}2 = V_{IH}$, $I_{I/O} = 0\text{mA}$	–	40	80	mA
Average Operating Current	I_{CC1}	Min. cycle, duty=100%, $I_{I/O} = 0\text{mA}$	–	60	110	mA
Standby Power Supply Current	I_{SB}	$\overline{\text{CS}}1 = V_{IH}$ or $\text{CS}2 = V_{IL}$	–	1	3	mA
	I_{SB1}^{**}	$\overline{\text{CS}}1 \geq V_{CC} - 0.2\text{V}$, $\text{CS}2 \geq V_{CC} - 0.2\text{V}$ or $\text{CS}2 \leq 0.2\text{V}$	–	0.02	2	mA
	I_{SB2}^{**}	$\text{CS}2 \leq 0.2\text{V}$	–	0.02	2	mA
Output Voltage	V_{OL}	$I_{OL} = 2.1\text{mA}$	–	–	0.4	V
	V_{OH}	$I_{OH} = -1.0\text{mA}$	2.4	–	–	V

* Typical limits are at $V_{CC} = 5.0\text{V}$, $T_a = 25^\circ\text{C}$ and specified loading.

** V_{IL} min = -0.3V

■ CAPACITANCE ($f = 1\text{MHz}$, $T_a = 25^\circ\text{C}$)

Item	Symbol	Test Condition	typ	max	Unit
Input Capacitance	C_{in}	$V_{in} = 0\text{V}$	–	6	pF
Input/Output Capacitance	$C_{I/O}$	$V_{I/O} = 0\text{V}$	–	8	pF

Note) This parameter is sampled and not 100% tested.

■ AC CHARACTERISTICS ($V_{CC} = 5V \pm 10\%$, $T_a = 0$ to $+70^\circ\text{C}$)

● AC TEST CONDITIONS

Input Pulse Levels: 0.8 to 2.4V

Input Rise and Fall Times: 10ns

Input and Output Timing Reference Level: 1.5V

Output Load: 1TTL Gate and $C_L = 100\text{pF}$ (including scope and jig)

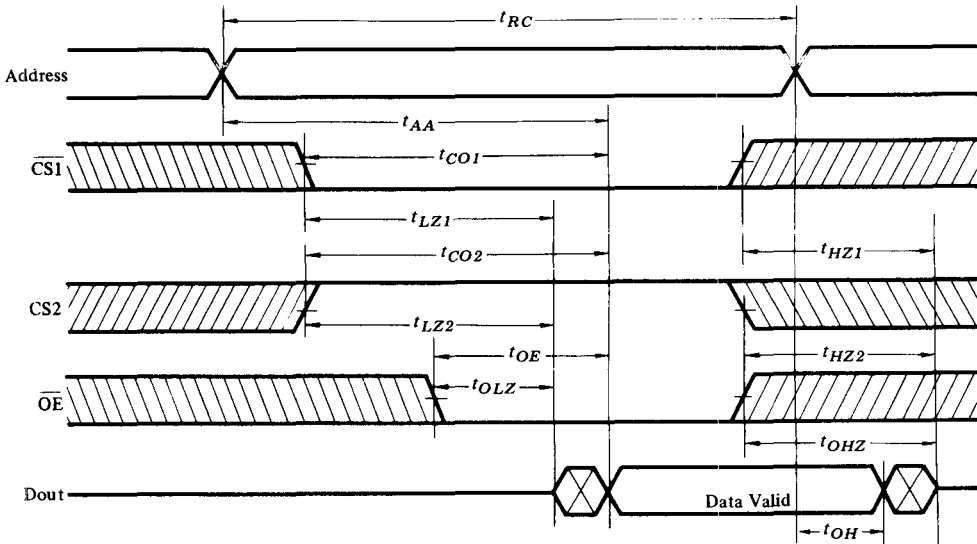
● READ CYCLE

Item	Symbol	HM6264P-10		HM6264P-12		HM6264P-15		Unit	
		min	max	min	max	min	max		
Read Cycle Time	t_{RC}	100	–	120	–	150	–	ns	
Address Access Time	t_{AA}	–	100	–	120	–	150	ns	
Chip Selection to Output	$\overline{\text{CS}}1$	t_{CO1}	–	100	–	120	–	150	ns
	$\text{CS}2$	t_{CO2}	–	100	–	120	–	150	ns
Output Enable to Output Valid	t_{OE}	–	50	–	60	–	70	ns	
Chip Selection to Output in Low Z	$\overline{\text{CS}}1$	t_{LZ1}	10	–	10	–	15	–	ns
	$\text{CS}2$	t_{LZ2}	10	–	10	–	15	–	ns
Output Enable to Output in Low Z	t_{OLZ}	5	–	5	–	5	–	ns	
Chip Deselection to Output in High Z	$\overline{\text{CS}}1$	t_{HZ1}	0	35	0	40	0	50	ns
	$\text{CS}2$	t_{HZ2}	0	35	0	40	0	50	ns
Output Disable to Output in High Z	t_{OHZ}	0	35	0	40	0	50	ns	
Output Hold from Address Change	t_{OH}	10	–	10	–	15	–	ns	

NOTES: 1 t_{HZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit condition and are not referred to output voltage levels.

2 At any given temperature and voltage condition, t_{HZ} max is less than t_{LZ} min both for a given device and from device to device.

• READ CYCLE

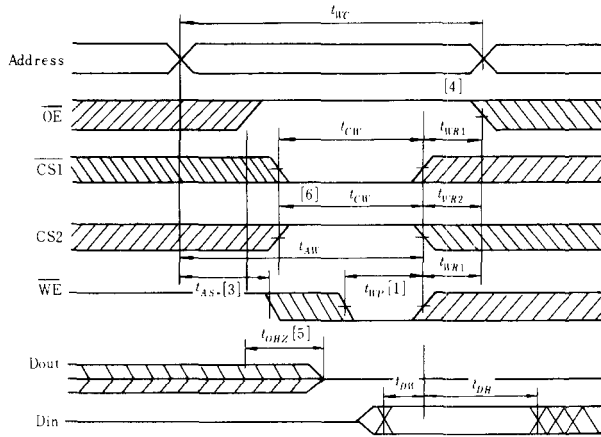


NOTE: 1) \overline{WE} is high for Read Cycle

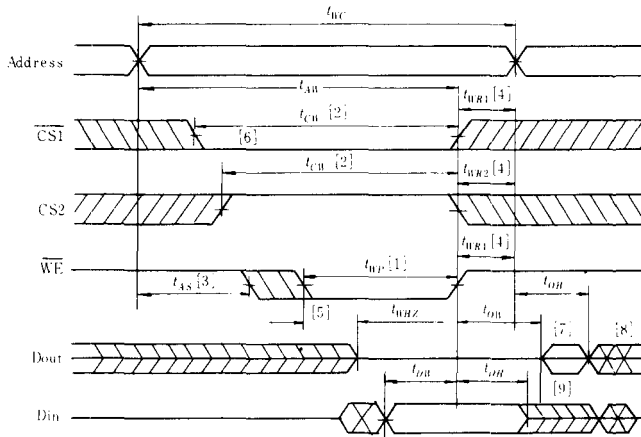
• WRITE CYCLE

Item	Symbol	HM6264P-10		HM6264P-12		HM6264P-15		Unit	
		min	max	min	max	min	max		
Write Cycle Time	t_{WC}	100	-	120	-	150	-	ns	
Chip Selection to End of Write	t_{CW}	80	-	85	-	100	-	ns	
Address Setup Time	t_{AS}	0	-	0	-	0	-	ns	
Address Valid to End of Write	t_{AW}	80	-	85	-	100	-	ns	
Write Pulse Width	t_{WP}	60	-	70	-	90	-	ns	
Write Recovery Time	CS1, WE	t_{WR1}	5	-	5	-	10	-	ns
	CS2	t_{WR2}	15	-	15	-	15	-	ns
Write to Output in High Z	t_{WHZ}	0	35	0	40	0	50	ns	
Data to Write Time Overlap	t_{DW}	40	-	50	-	60	-	ns	
Data Hold from Write Time	t_{DH}	0	-	0	-	0	-	ns	
\overline{OE} to Output in High Z	t_{OHZ}	0	35	0	40	0	50	ns	
Output Active from End of Write	t_{OW}	5	-	5	-	10	-	ns	

• WRITE CYCLE (1) (\overline{OE} clock)

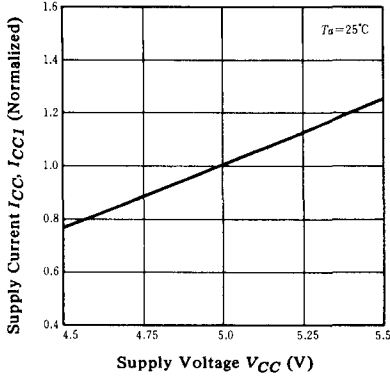


• WRITE CYCLE (2) (\overline{OE} Low Fix)

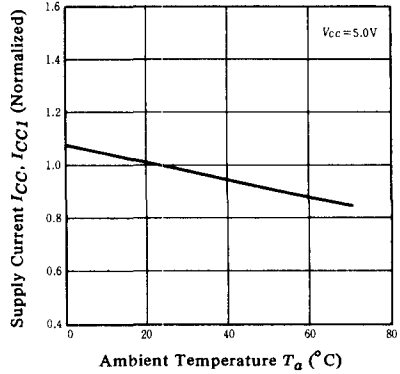


- NOTES: 1) A write occurs during the overlap of a low $\overline{CS1}$, a high $\overline{CS2}$ and a low \overline{WE} . A write begins at the latest transition among $\overline{CS1}$ going low, $\overline{CS2}$ going high and \overline{WE} going low. A write ends at the earliest transition among $\overline{CS1}$ going high, $\overline{CS2}$ going low and \overline{WE} going high. t_{WP} is measured from the beginning of write to the end of write.
- 2) t_{CW} is measured from the later of $\overline{CS1}$ going low or $\overline{CS2}$ going high to the end of write.
- 3) t_{AS} is measured from the address valid to the beginning of write.
- 4) t_{WR} is measured from the end of write to the address change.
 t_{WR1} applies in case a write ends at $\overline{CS1}$ or \overline{WE} going high.
 t_{WR2} applies in case a write ends at $\overline{CS2}$ going low.
- 5) During this period, I/O pins are in the output state, therefore the input signals of opposite phase to the outputs must not be applied.
- 6) If $\overline{CS1}$ goes low simultaneously with \overline{WE} going low or after \overline{WE} going low, the outputs remain in high impedance state.
- 7) t_{OH} is the same phase of the latest written data in this write cycle.
- 8) t_{DH} is the read data of next address.
- 9) If $\overline{CS1}$ is low and $\overline{CS2}$ is high during this period, I/O pins are in the output state. Therefore, the input signals of opposite phase to the outputs must not be applied to them.

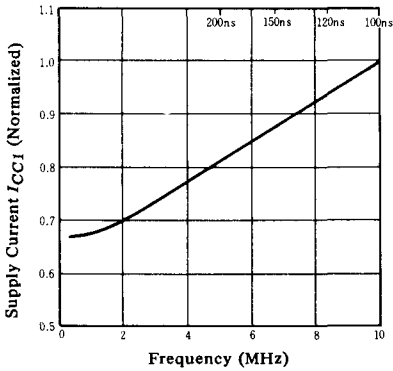
SUPPLY CURRENT vs. SUPPLY VOLTAGE



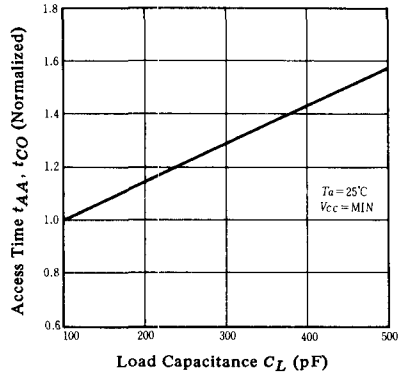
SUPPLY CURRENT vs. AMBIENT TEMPERATURE



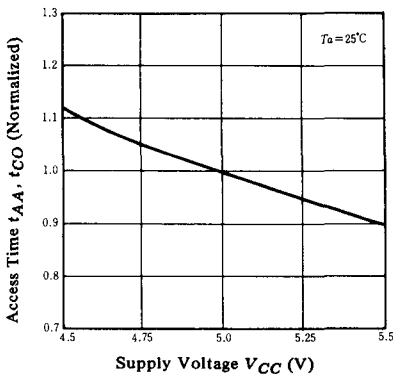
SUPPLY CURRENT vs. FREQUENCY



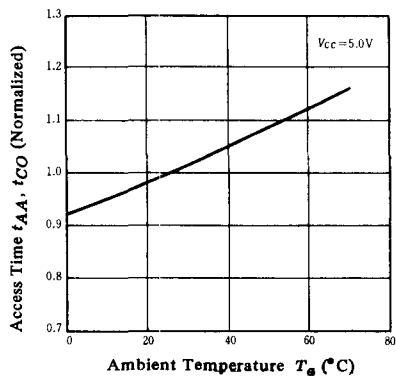
ACCESS TIME vs. LOAD CAPACITANCE



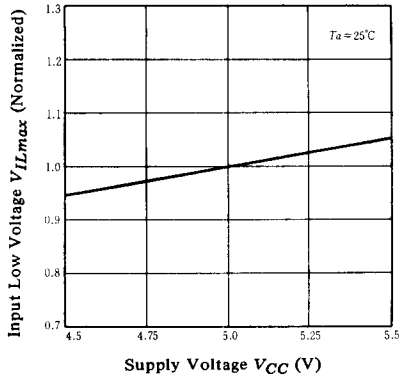
ACCESS TIME vs. SUPPLY VOLTAGE



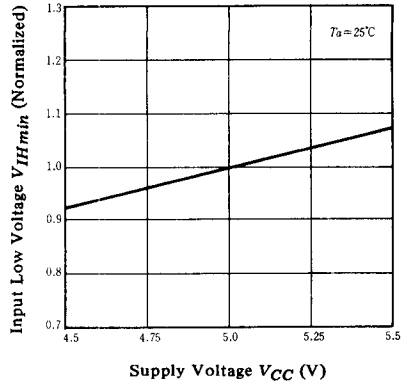
ACCESS TIME vs. AMBIENT TEMPERATURE



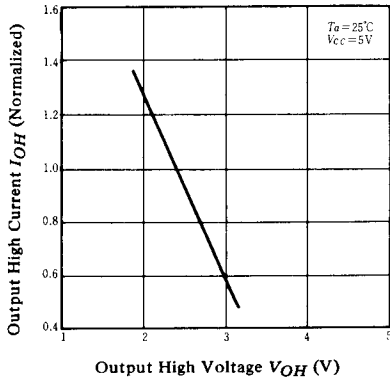
INPUT LOW VOLTAGE vs. SUPPLY VOLTAGE



INPUT HIGH VOLTAGE vs. SUPPLY VOLTAGE



OUTPUT CURRENT vs. OUTPUT VOLTAGE



OUTPUT CURRENT vs. OUTPUT VOLTAGE

